

PHOTO DIODE SILICON PIN LED LA	MPS	LPD638	83	SE	RIES			
Package Dimension				Description				
1.5MAX	ls ±0.25 unk	1.ANODE 2.CATHODE ess otherwise noted	P/N pho package filter and emission tabs arra spacing can vert arrays c arrange suitable operatio particula illuminar outstand high cut- times. They are sound tr	todiode that sin d are als n their to anged in due to ically be an be ro ment ve for dioc not the si arly favo note the ding for -off freq e particu ansmis ode of l	s incorp multane so Trans erminals n 2.54m their de e assem ealized ersatile p des as v gnal no orable ev p/N pho low juno ularly su sion and _PD638	orated ously s sparent s are so im cent sign the bled of bled of by mult ohotode vell as ven at l otodiod ction ca and fas uitable f d remot	t for infrared oldering er to cente e diodes n pc boards iple etectors are voltaic cell o is ow e are pacitance t switching for IR te control odiode is	
Characteristic		Symbol		Rating			Unit	
Reverse Break Down Voltage		VBR		30			V	
Power Dissipation	PD			150			mW	
Operating Temperature	Topr			-30 - +60				
Storage Temperature		Tstg		-40 - +60				
ELECTRICAL CHARAC	TERIS	FICS AT (TA=)					
Characteristic	Symbol	Test Cond	dition	Min	Тур	Max	Unit	
Dark Current	lo	VR=10V Ee=0n	nW/cm²	-	1.0	30	nA	
Short Circuit Current	lsc	V _R =5V P=940nm Ee=0.5mW/cm ²		1.5	2.0	-	uA	
Open Circuit Voltage	Voc	P=940nm Ee=0.5mW/cm ²		_	350	-	mV	
Total Capacitance CT		VR=3V f=1MHZ Ee=0mW/cm		-	20	-	pF	
Peak Wavelength of Max Sensitivity	smax			-	940	-	nm	
Rise Time,Fall Time	tr,tf	VR=10V RL=1K		-	50	-	ns	